

What is claimed is:

1. A stacked chip package comprising:
a board including a plurality of board pads and a plurality of dummy board pads;
5 a plurality of chips each having at least one bonding pad, said plurality of chips being
stacked one atop the other on the board; and
at least one heat transfer wire disposed between the chips,
wherein at least one end of each heat transfer wire is connected to at least one dummy
board pad, and at least one bonding pad is electrically connected to at least one of the board
10 pads.
2. A stacked chip package according to claim 1, wherein both ends of each heat
transfer wire are connected to the plurality of dummy board pads.
- 15 3. A stacked chip package according to claim 1, further comprising at least one
dummy bonding pad on the chips, wherein at least one end of at least one heat transfer wire is
connected to at least one of the dummy bonding pads on the chips.
4. A stacked chip package according to claim 3, wherein each dummy bonding
20 pad is separated from each bonding pad.
5. The stacked chip package according to claim 3, wherein the at least one
dummy bonding pad is provided on substantially the center portion of the lower chip.
- 25 6. The stacked chip package according to claim 3, wherein one end of each heat
transfer wire is connected to the dummy bonding pad by stitch bonding, and the other end is
connected to the dummy board pad by ball bonding.
7. A stacked chip package according to claim 1, wherein a plurality of solder
30 balls are joined to the board, said solder balls being electrically connected to the board pads.
8. A stacked chip package according to claim 1, wherein at least one of the heat
transfer wires is connected to ground.

9. A stacked chip package according to claim 1, wherein the chips are adhered to each other by an adhesive layer.

10. A stacked chip package according to claim 9, wherein at least one heat transfer wire is disposed within the adhesive layer.

11. A stacked chip package according to claim 1, wherein at least one heat transfer wire is disposed on the top of the stacked chips.

12. A stacked chip package according to claim 1, wherein each heat transfer wire is a conventional bonding wire.

13. A method for producing a stacked chip package comprising:
providing a board including at least one board pad and least one dummy board pad;
providing a plurality of chips each having at least one bonding pad;
stacking said plurality of chips being one atop the other on the board; and
disposing at least one heat transfer wire between the chips, at least one end of each heat transfer wire being connected to at least one dummy board pad for heat dissipation purposes, and each bonding pad being electrically connected to at least one of the board pads.

14. A method according to claim 13, wherein both ends of each heat transfer wire are connected to a dummy board pad.

15. A method according to claim 13, wherein at least one dummy bonding pad is provided on the chips, and at least one end of at least one heat transfer wire is connected to at least one of the dummy bonding pads on the chips.

16. A method according to claim 15, wherein each dummy bonding pad is separated from each bonding pad.

17. A method according to claim 13, wherein a plurality of solder balls are joined to the board, said solder balls being electrically connected to the board pads.

18. A method according to claim 13, wherein at least one of the heat transfer wires is connected to ground.

19. A method according to claim 13, wherein the chips are adhered to each other
5 by an adhesive layer.

20. A method according to claim 19, wherein at least one heat transfer wire is disposed within the adhesive layer.